November 12, 2026

To whom it may concern

Name of company	V-Technology Co., Ltd.
Representative	Shigeto Sugimoto / President and CEO
	(TSE Prime Market / Code No: 7717)
Name of company	LE-TECHNOLOGY Co., Ltd.
Representative	Duk Lee / President, CEO
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LAMBDI DI Lithography System
Mass-Production Systems Ordered by Overseas Package Manufacturers

LE-TECHNOLOGY Co., Ltd. ("LET"), a consolidated subsidiary of V-Technology Co., Ltd. (the "Company"), has received orders of approximately ¥7.0 billion from overseas package manufacturers for mass-production units of "LAMBDI," its DI lithography system for package substrates. As cumulative orders for DI lithography systems for substrates and interposers since the fourth quarter of the fiscal year ended March 31, 2026 have reached approximately ¥16.0 billion, the Company hereby announces the details as described below.

Details

1. About the Orders

In the semiconductor industry, the spread of generative AI is driving higher integration and larger sizes of high-performance semiconductors, and the package substrates on which they are mounted are required to support even finer wiring and larger substrate sizes. DI (direct imaging) lithography systems, which draw circuit patterns directly onto substrates without using masks, are attracting attention as a lithography method capable of meeting these requirements.

These orders reflect growing demand for advanced packaging for high-performance semiconductors, with adoption now expanding from domestic package manufacturers to overseas package manufacturers. LAMBDI's multi-point real-time autofocus function, which sets it apart from conventional DI lithography systems, enables high-precision fine patterns to be formed across the entire surface of large substrates. We believe that this performance, together with the large-area, high-precision lithography technology our group has cultivated, was highly evaluated.

The V-Technology Group will continue to create innovative technologies that support the evolution of semiconductors and electronic devices, and contribute to the development of society.

2. Details of the Orders

Customer	Overseas package manufacturers
Product	“LAMBDI” DI lithography system for package substrates (mass-production units)
Order amount	Approximately ¥7.0 billion
Expected timing of sales recognition	Fiscal year ending March 31, 2028 or later
Cumulative orders for mass-production units	Approximately ¥16.0 billion (including orders received from a domestic package manufacturer in the fourth quarter of the fiscal year ended March 31, 2026)

3. Impact on Financial Results

These orders are expected to be recorded as sales in the fiscal year ending March 31, 2028 or later.

Accordingly, these orders will have no impact on the consolidated financial results for the fiscal year ending March 31, 2027.

End

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